

DIP39, 54.50x31.00x5.60, 1.78P EP-2  
CASE MODGX  
ISSUE B

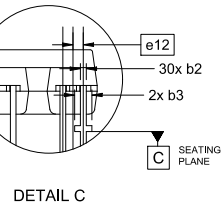
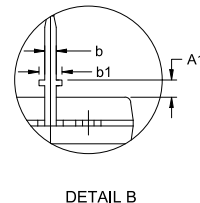
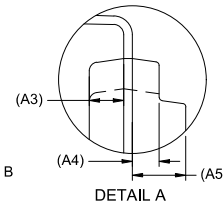
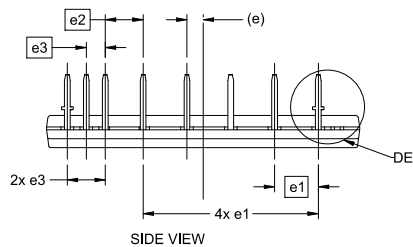
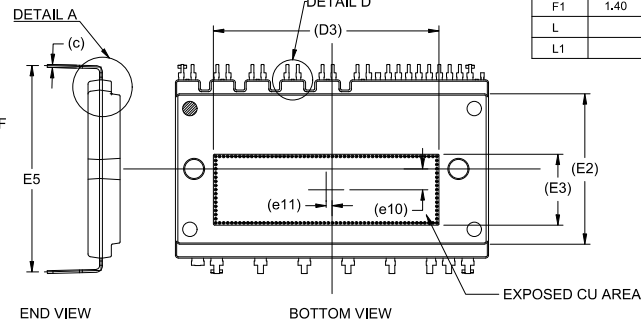
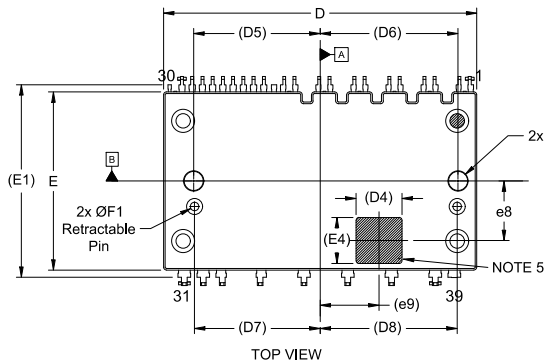
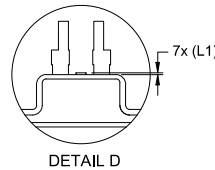
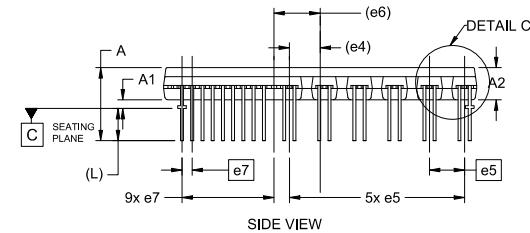
DATE 05 MAY 2025

NOTES:

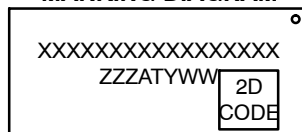
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b and c APPLY TO THE PLATED LEADS AND ARE MEASURED BETWEEN 1.00 AND 2.00 FROM THE LEAD TIP
4. POSITION OF THE LEAD IS DETERMINED AT THE BASE OF THE LEAD WHERE IT EXITS THE PACKAGE BODY
5. AREA FOR 2D BAR CODE
6. SHORTENED/CUT PINS ARE 2.5, 8, 11, 14, 17, 19, 29, 30 AND 39
7. DIMENSIONS "D" AND "E" DO NOT INCLUDE THE SIDE FLASH PROTRUSION WHICH IS ~0.12 FOR EACH SIDE

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	12.20	12.7	13.2
A1	1.00	1.50	2.00
A2	5.50	5.60	5.70
A3		2.00 REF	
A4		1.55 REF	
A5		3.10 REF	
b	0.90	1.00	1.10
b1	1.90	2.00	2.10
b2	0.40	0.50	0.60
b3	1.40	1.50	1.60
c		0.50 REF	
D	54.40	54.50	54.60
D3		39.25 REF	
D4		8.00 REF	
D5		22.00 REF	
D6		24.00 REF	
D7		21.85 REF	
D8		23.85 REF	

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
E	30.90	31.00	31.10
E1		33.50 REF	
E2		26.14 REF	
E3		12.35 REF	
E4		8.00 REF	
E5	35.40	35.90	36.40
e		2.81 REF	
e1		7.62 BSC	
e2		6.60 BSC	
e3		3.30 BSC	
e4		5.35 REF	
e5		6.10 BSC	
e6		8.02 REF	
e7		1.78 BSC	
e8		10.35 REF	
e9		10.25 REF	
e10		3.60 REF	
e11		1.00 REF	
e12		0.89 BSC	
F	3.20	3.30	3.40
F1	1.40	1.50	1.60
L		5.60 REF	
L1		0.10 REF	



GENERIC  
MARKING DIAGRAM\*



XXXXX = Specific Device Code  
ZZZ = Assembly Lot Code  
AT = Assembly & Test Location  
Y = Year  
WW = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	DIP39, 54.50x31.00x5.60, 1.78P EP-2	PAGE 1 OF 1

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